捷多邦,专业PCB打样工厂,24小时加**SN74**AVC16646 16-BIT BUS TRANSCEIVER AND REGISTER WITH 3-STATE OUTPUTS

SCES181F-DECEMBER 1998-REVISED JUNE 2005

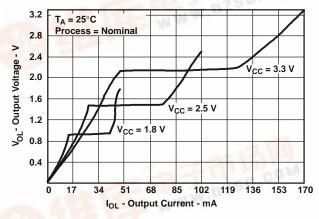
FEATURES

- Member of the Texas Instruments Widebus™
 Family
- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- DOC™ (Dynamic Output Control) Circuit Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation
- Dynamic Drive Capability Is Equivalent to Standard Outputs With I_{OH} and I_{OL} of ± 24 mA at 2.5-V V_{CC}

- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- Package Options Include Plastic Thin Shrink
 Small-Outline (DGG) and Thin Very
 Small-Outline (DGV) Packages

DESCRIPTION

A Dynamic Output Control (DOC^{TM}) circuit is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical V_{OL} vs I_{OL} and V_{OH} vs I_{OH} curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, AVC Logic Family Technology and Applications, literature number SCEA006, and Dynamic Output Control (DOC^{TM}) Circuitry Technology and Applications, literature number SCEA009.



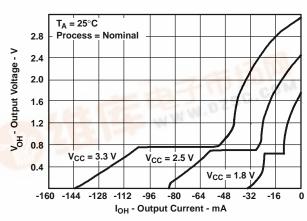


Figure 1. Output Voltage vs Output Current

This 16-bit bus transceiver and register is operational at 1.2-V to 3.6-V V_{CC} , but is designed specifically for 1.65-V to 3.6-V V_{CC} operation.

The SN74AVC16646 can be used as two 8-bit transceivers or one 16-bit transceiver. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 2 illustrates the four fundamental bus-management functions that can be performed with the SN74AVC16646.

Output-enable ($\overline{\text{OE}}$) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both. The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data.

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DESCRIPTION (CONTINUED)

The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. DIR determines which bus receives data when \overline{OE} is low. In the isolation mode (\overline{OE} high), A data may be stored in one register and/or B data may be stored in the other register.

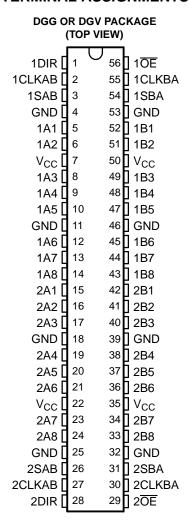
When an output function is disabled, the input function still is enabled and may be used to store and transmit data. Only one of the two buses, A or B, can be driven at a time.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The SN74AVC16646 is characterized for operation from -40°C to 85°C.

TERMINAL ASSIGNMENTS





SCES181F-DECEMBER 1998-REVISED JUNE 2005

FUNCTION TABLE (EACH 8-BIT TRANSCEIVER/REGISTER)

		INP	UTS			DATA	A I/Os	OPERATION OR FUNCTION
ŌĒ	DIR	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
Х	Х	1	Х	Х	Х	Input	Unspecified (1)	Store A, B unspecified ⁽¹⁾
X	X	Χ	\uparrow	Χ	Χ	Unspecified ⁽¹⁾	Input	Store B, A unspecified (1)
Н	Х	1	1	Х	Х	Input	Input	Store A and B data
Н	X	H or L	H or L	Χ	Χ	Input disabled	Input disabled	Isolation, hold storage
L	L	Χ	Χ	Χ	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	Χ	Н	Output	Input	Stored B data to A bus
L	Н	Х	Х	L	Х	Input	Output	Real-time A data to B bus
L	Н	H or L	Χ	Н	Χ	Input	Output	Stored A data to B bus

⁽¹⁾ The data-output functions may be enabled or disabled by various signals at $\overline{\text{OE}}$ and DIR. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



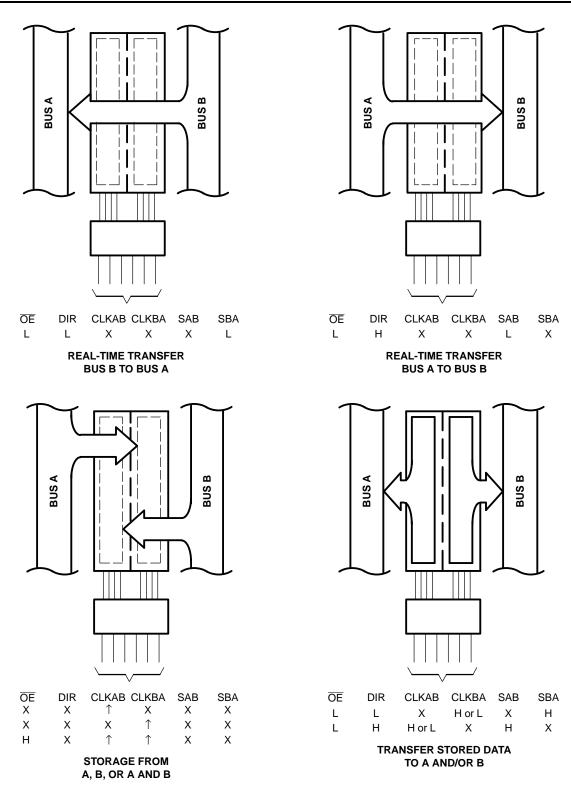
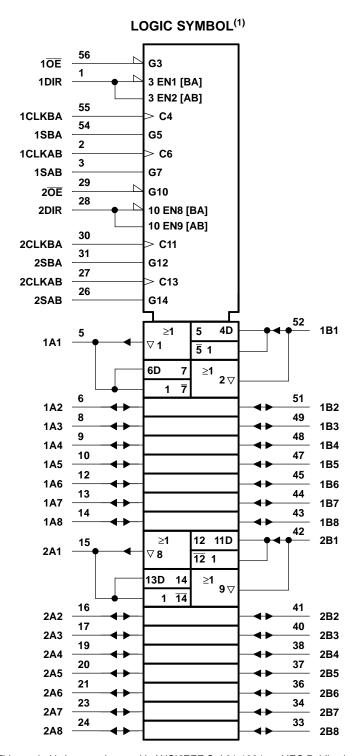


Figure 2. Bus-Management Functions

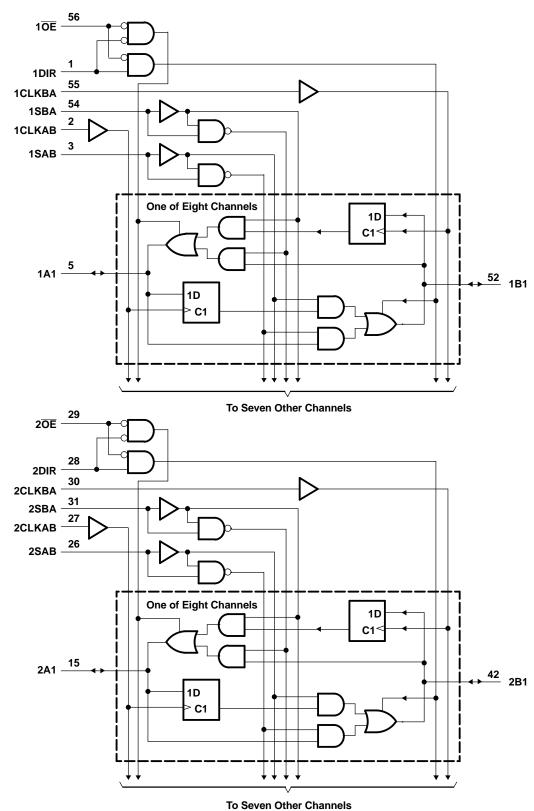




(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



LOGIC DIAGRAM (POSITIVE LOGIC)





SCES181F-DECEMBER 1998-REVISED JUNE 2005

Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT	
V_{CC}	Supply voltage range	-0.5	4.6	V		
VI	Input voltage range (2)		-0.5	4.6	V	
Vo	Voltage range applied to any input/output when the output is in the high-impedance or power-off	-0.5	4.6	V		
Vo	Voltage range applied to any input/output when the ou	-0.5	V _{CC} + 0.5	V		
I _{IK}	Input clamp current	Input clamp current $V_1 < 0$				
I _{OK}	Output clamp current	V _O < 0		-50	mA	
Io	Continuous output current			±50	mA	
	Continuous current through each V _{CC} or GND			±100	mA	
0	Deckers thermal impedance (4)	DGG package		64	°C/W	
θ_{JA}	Package thermal impedance (4)	DGV package		48	C/VV	
T _{stg}	Storage temperature range	-65	150	°C		

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

⁽²⁾ The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51.





Recommended Operating Conditions⁽¹⁾

			MIN	MAX	UNIT	
V _{CC}	Supply voltage	Operating	1.2	3.6	V	
		V _{CC} = 1.2 V	V _{CC}			
		V _{CC} = 1.4 V to 1.6 V	0.65 × V _{CC}			
V_{IH}	High-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V _{CC}		V	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7			
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	2			
		V _{CC} = 1.2 V		GND		
V_{IL}		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		$0.35 \times V_{CC}$		
	Low-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$	V	
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7		
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		0.8		
V_{I}	Input voltage		0	3.6	V	
V	Output voltage	Active state	0	V_{CC}	V	
Vo	Output voltage	3-state	0	3.6	V	
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		-2		
	Static high-level output current (2)	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		-4	mA	
I _{OHS}	Static high-level output current	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-8	MA	
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		-12		
		V _{CC} = 1.4 V to 1.6 V		2		
I _{OLS}	Static low-level output current ⁽²⁾	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		4	mA	
	Static low-level output currents	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		8	ША	
		V _{CC} = 3 V to 3.6 V		12		
Δt/Δν	Input transition rise or fall rate	V _{CC} = 1.4 V to 3.6 V		5	ns/V	
T _A	Operating free-air temperature		-40	85	°C	

 ⁽¹⁾ All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
 (2) Dynamic drive capability is equivalent to standard outputs with I_{OH} and I_{OL} of ±24 mA at 3.3-V V_{CC}. See Figure 1 for V_{OL} vs I_{OL} and V_{OH} vs I_{OH} characteristics. Refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number SCEA006, and *Dynamic Output Control (DOC™) Circuitry Technology and Applications*, literature number SCEA009.



SCES181F-DECEMBER 1998-REVISED JUNE 2005

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

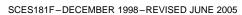
	PARAMETER	TEST CO	NDITIONS	V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT	
		$I_{OHS} = -100 \mu\text{A}$		1.2 V to 3.6 V	V _{CC} - 0.2				
		$I_{OHS} = -2 \text{ mA},$	$V_{IH} = 0.91 \ V$	1.4 V	1.05				
V_{OH}		$I_{OHS} = -4 \text{ mA},$	$V_{IH} = 1.07 V$	1.65 V	1.2			V	
		$I_{OHS} = -8 \text{ mA},$	$V_{IH} = 1.7 V$	2.3 V	1.75				
		$I_{OHS} = -12 \text{ mA},$	$V_{IH} = 2 V$	3 V	2.3				
		$I_{OLS} = 100 \mu A$		1.2 V to 3.6 V			0.2		
		$I_{OLS} = 2 \text{ mA},$	$V_{IL} = 0.49 \ V$	1.4 V			0.4		
V_{OL}		$I_{OLS} = 4 \text{ mA},$	$V_{IL} = 0.57 \ V$	1.65 V			0.45	V	
		$I_{OLS} = 8 \text{ mA},$	V _{IL} = 0.7 V	2.3 V			0.55		
		$I_{OLS} = 12 \text{ mA},$	$V_{IL} = 0.8 V$	3 V			0.7		
I_{\parallel}	Control inputs	$V_I = V_{CC}$ or GND		3.6 V			±2.5	μΑ	
I _{off}		V_I or $V_O = 3.6 \text{ V}$		0			±10	μΑ	
I _{OZ} ⁽²⁾)	$V_O = V_{CC}$ or GND,	$V_I = V_{CC}$	3.6 V			±12.5	μΑ	
I _{CC}		$V_I = V_{CC}$ or GND,	I _O = 0	3.6 V			40	μΑ	
	CLK inpute			2.5 V		3			
Ci	CLK inputs	V – V or CND		3.3 V		3		pF	
Ci	Control innute	$V_I = V_{CC}$ or GND		2.5 V		3.5		рг	
	Control inputs			3.3 V		3.5			
C	A or P porto	V – V or CND		2.5 V		8		~F	
C _{io}	A or B ports	$V_O = V_{CC}$ or GND		3.3 V		8		pF	

Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3 through Figure 6)

			V _{CC} =	1.2 V	V _{CC} = ± 0.	1.5 V 1 V	V _{CC} = ± 0.1		V _{CC} = 1 ± 0.2		V _{CC} = 3 ± 0.3	3.3 V 3 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock freque	ncy						150		250		350	MHz
t _w	Pulse duration	CLKAB or CLKBA high or low					3.3		2		1.4		ns
t _{su}	Setup time	A before CLKAB↑ or B before CLKBA↑	2.1		1.6		1.2		0.9		0.8		ns
t _h	Hold time	A after CLKAB↑ or B after CLKBA↑	1.3		1		0.8		0.6		0.6		ns

⁽¹⁾ Typical values are measured at $T_A = 25^{\circ}C$. (2) For I/O ports, the parameter I_{OZ} includes the input leakage current.





Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3 through Figure 6)

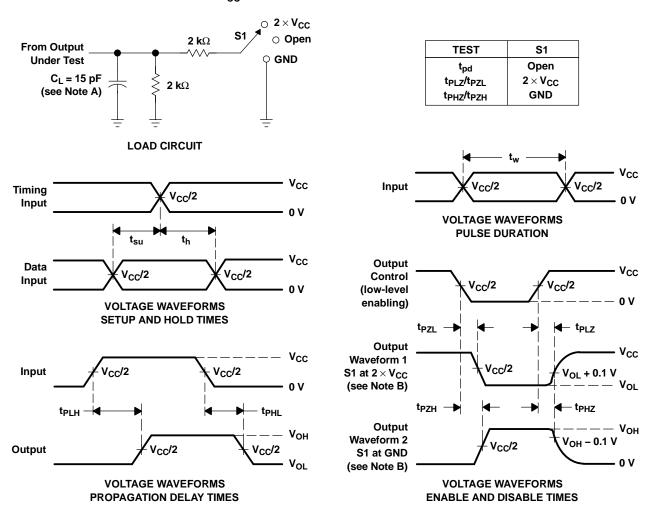
PARAMETER	FROM (INPUT)	_			_	-	_		_	_	_	_	-	TO (OUTPUT)	V _{CC} = 1.2 V	1.2 V $V_{CC} = 1.5 V$ $\pm 0.1 V$		V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
		(OUTPUT)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX													
f _{max}						150		250		350		MHz												
	A or B	B or A	4.2	1.6	4.8	1.5	4.3	1.2	3.1	0.9	2.6													
t _{pd}	CLKAB or CLKBA	A or B	5.9	2.2	7.4	1.9	6.1	1.3	4	1	3.3	ns												
	SAB or SBA		8.2	2.6	10	2.4	6.3	1.8	5.1	1.5	4													
t _{en}	ŌĒ	A or B	6.5	2.2	8	1.9	7	1.4	4.6	1.1	4	ns												
t _{dis}	ŌĒ	A or B	6.7	2.6	8	2.6	7.2	1.4	4.3	1.4	4.2	ns												
t _{en}	DIR	A or B	6.9	2.2	8.7	1.9	7.4	1.4	5	1.1	4.3	ns												
t _{dis}	DIR	A or B	7.5	2.6	8.7	2.6	7.6	1.4	4.5	1.4	4.3	ns												

Operating Characteristics

 $T_A = 25^{\circ}C$

	PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	$V_{CC} = 3.3 \text{ V}$	UNIT
	FARAMETER	TEST CONDITIONS	TYP	TYP	TYP	ONI	
0	Dower dissinction conscitones	Outputs enabled	C 0 f 10 MHz	62	73	120	۲
C _{pd}	Power dissipation capacitance	Outputs disabled	$C_L = 0$, $f = 10 \text{ MHz}$	25	29	34	pF

PARAMETER MEASUREMENT INFORMATION V_{CC} = 1.2 V AND 1.5 V ± 0.1 V

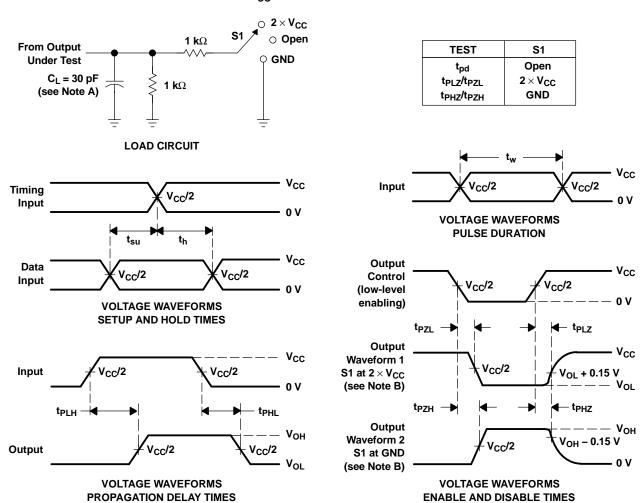


- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_r \leq$ 2 ns, $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 3. Load Circuit and Voltage Waveforms



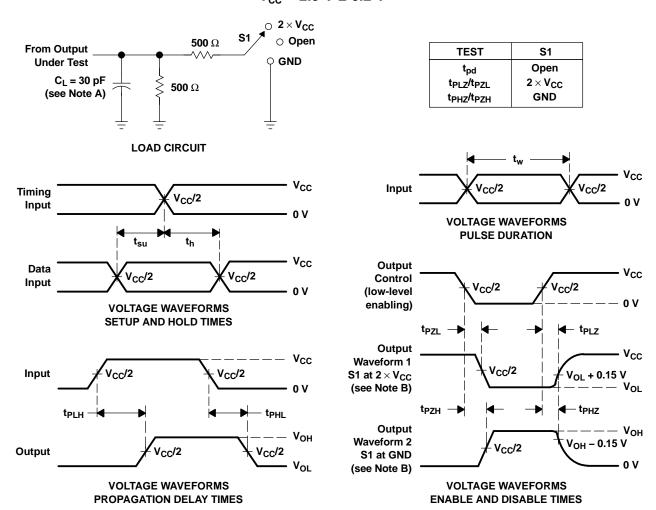
PARAMETER MEASUREMENT INFORMATION $V_{cc} = 1.8 \text{ V} \pm 0.15 \text{ V}$



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 4. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$

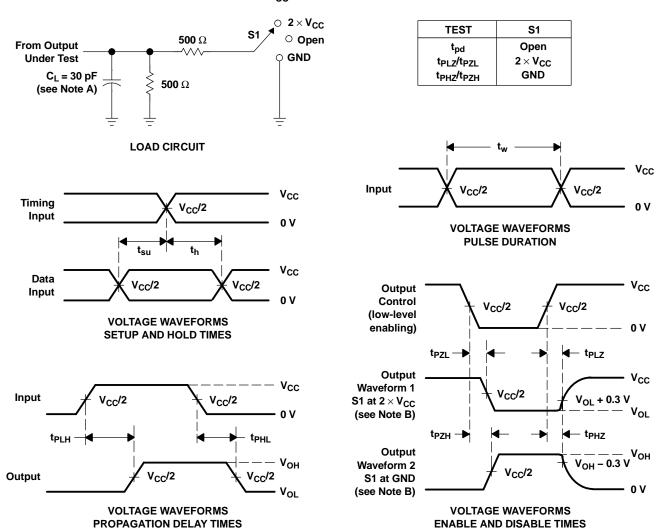


- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_r \leq$ 2 ns, $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd}.

Figure 5. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_r \leq$ 2 ns, $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en}.
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 6. Load Circuit and Voltage Waveforms



PACKAGE OPTION ADDENDUM

5-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AVC16646DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74AVC16646DGVRE4	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVC16646DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AVC16646DGVR	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

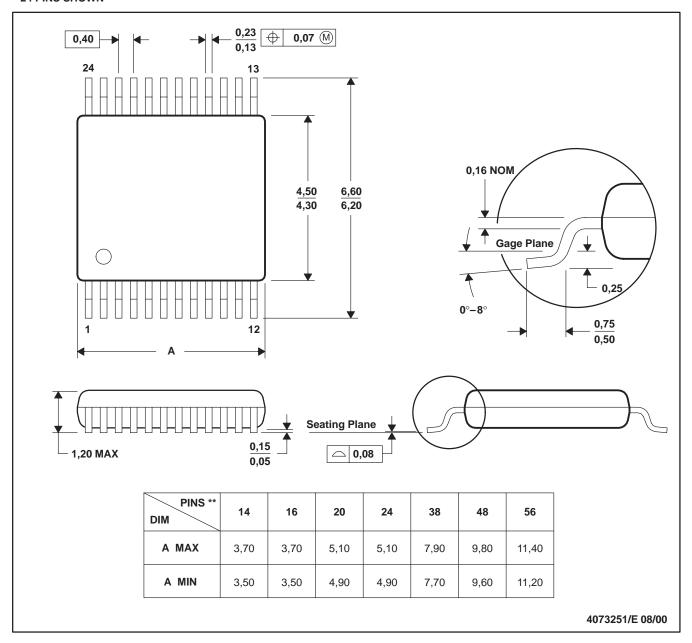
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DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

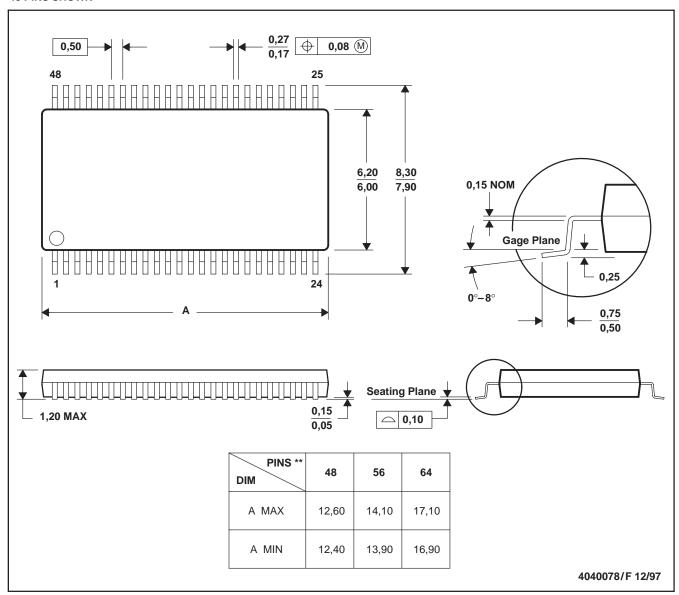
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153 14/16/20/56 Pins – MO-194



DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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